

OWEGO, NEW YORK  
PCB FABRICATION

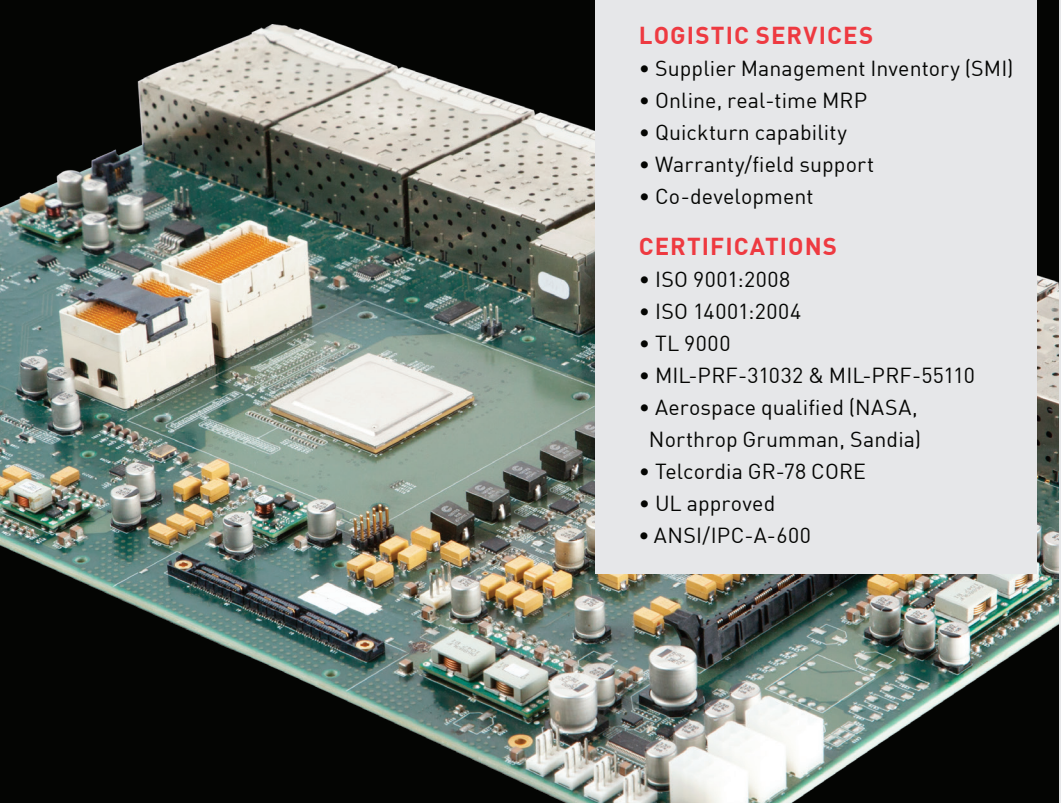


SANMINA®

# HIGH VOLUME PRODUCTION FOR HIGH TECHNOLOGY PRODUCTS

The Sanmina Owego facility offers the most advanced printed circuit board (PCB) and backplane technologies to the world's leading companies in computing & storage, defense & aerospace, and telecommunications. With 300,000 square feet of manufacturing capacity, we specialize in mid-to-high volume production of advanced PCBs, as well as short cycle time NPI/QTA requirements. Through our superior capabilities in advanced interconnect and integrated, high speed components, Sanmina Owego designs custom solutions for the most complex products. We also combine our extensive connector expertise and in-house characterization of new laminates to design and produce turnkey, high-speed backplanes. Our comprehensive technical capabilities include Buried Capacitance®, high performance materials, sequential lamination, sub assemblies, high density registration & class III requirements, high layer count, large format multilayer PCBs and high density interconnects. For your most advanced printed circuit boards and backplanes, partner with Sanmina today.

To learn more, visit [sanmina.com](http://sanmina.com).



## LOGISTIC SERVICES

- Supplier Management Inventory (SMI)
- Online, real-time MRP
- Quickturn capability
- Warranty/field support
- Co-development

## CERTIFICATIONS

- ISO 9001:2008
- ISO 14001:2004
- TL 9000
- MIL-PRF-31032 & MIL-PRF-55110
- Aerospace qualified (NASA, Northrop Grumman, Sandia)
- Telcordia GR-78 CORE
- UL approved
- ANSI/IPC-A-600

## MANUFACTURING CAPABILITIES

- Quickturn & High Volume
- Latest High-Speed Materials
- Up to 70 Layers
- Board Thickness - Up to 0.500"
- Panel Sizes Up to 24" x 54"
- Laser Microvias
- Multiple Metal Finishes
- Advanced Materials
- HDI Technology & Stacked Microvias
- Sequential Lamination
- Buried Passives
- Via Fill

## ENGINEERING CAPABILITIES

- New Product Introduction (NPI)
- DFM and Failure Analysis
- Product, Process and Quality
- Signal Integrity Lab
- Fusion Bonding
- Hybrid Laminate & RF Constructions
- PTFE, Ceramic, Low-loss

## TESTING CAPABILITIES

- Impedance, Capacitance
- X-ray, AOI
- IST Testing
- Perfect Test
- Four Wire Kelvin

## TECHNOLOGIES

- Variety of surface finishes and materials
- Lead-free processes
- High Reliability, High Aspect Ratio PTHs
- HDI and stacked microvias
- Via-in-pad interconnect
- High reliability, high aspect ratio PTHs
- Failure analysis & reliability (SEM, EDX, SIR, etc.)
- Connector expertise (Tyco, Molex, FCI, Amphenol)